Standardized Information for Process/Product Change Notification (PCN)

Based on the JEDEC Standard JESD46 standard (latest release)

Not for publication unless permission is grant	ed by LEM 1. PCN basic data	Form
1.1 Company Life Energy Motion	LEM International SA Route du Nant d'Avril 152 1217 Meyrin Switzerland	
1.2 PCN No.	PCN-037_2025_0-OMTS2512701	by Z
1.3 Title of PCN	Primary pins+plating supplier & plating process]\E
1.4 Product Category	Electronic module - Current sensor	I-R
1.5 Issue date	2025/07/21	Revision
1.6 PCN revision history (optional)	1.7 Issue date of previous 1.8 Delta to previous revision (optional) revision (optional)	ion 5.0
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	2. PCN Team					
2.1 Contact supplier						
2.1.1 Name	Magdalena Peycheva - Product L	ife Cycle Coordinator				
2.1.2 Phone						
2.1.3 Email	Mpy@lem.com	Mpy@lem.com				
2.2 Team supplier (optional)	-					
2.2.1 Name (optional)	2.2.2 Phone (optional)	2.2.3 Email (optional)				
Stéphane Rollier - Product Life Cycle manager	0041227061449	sro@lem.com				

		3. Changes	
No.	3.0 Ident	3.1 Category	3.2 Type of change
#1	SEM-PA-14	PROCESS - ASSEMBLY	Change in process technology (e.g. sawing, die attach, bonding, moulding, plating, trim and form, lead frame preperation,)
#2	SEM-PA-16	PROCESS - ASSEMBLY	Change of direct material supplier

	4. Description of change					
	Old	New				
	Primary copper pins (wire), plating: Electroplating, Tin (Sn), thickness is 4 um average (between 3-6 um). Primary copper pins material: C1100 oxygen-free copper, 99.99% of copper.	Primary copper pins (wire) plating: Hot-dipping, SAC305 (SnAgCu alloy), thickness is 0.5um~5um. 2.8% < Ag < 4.2% 0.3% < Cu < 0.9% Tin for the remainder.				
Change #2		New supplier for primary copper pins (wire) + plating. Same copper material (spec) used as before.				
	No impact on form, fit, function, reliability, data sheet Process change a bit as primary copper pins (wire) p SAC305.					
4.2 Reference parts with customer number (optional)						

			5. R	eason / motiva	tion for chang	e			
5.1 Motivation			Whisker mit	igation					
5.2 Addition	al explanation (option	nal)							
6.1 Descript	i a m			ng of parts / tra n the marking o	-	nange			
6.1 Descript	IOII			ensured by date					
			11.0000						
				7. Timing / s	schedule				
7.1 Date of c	ualification results		2024/08/13	g,	T				
7.1 Bute of e	quannoution results		2024/00/10						
7.2 Last orde	er date (optional)								
7 3 Last deli	very date (optional)								
7.5 East dell	very date (optional)								
7.4 Intended	start of delivery		2025/09/05						
7 5 Qualifica	ition samples availab	162	YES						
7.0 Quamica	and Samples availab								
7.6 Custome	er feedback required	until	2025/09/01						
0.4.Danamin4	! a .a			B. Qualification		latina) nanant	a a lala na la ilita y na na	out overlable	
8.1 Descript	an/report, AEC-Q)		inspection re	eport, Raw mate	enai anaiysis (p	naung) report, s	solderability rep	ort avallable	on request.
	tion report and quali	ification				issue date	13/08/2024		
results	ition report and quan	lication	will be availab	le at date	•	issue date	13/00/2024		
			0 legget to a		Jr annan	1			
			9. input to c	ustomer for ris	sk assessmen	process			
<u></u>		_							
	10. Attachme	nts (e.g. new	datasheet, a	dditional docur	mentation, pic	tures, process	s flow, sample	plan,)	
				11. Affecte	d parts				
		11.1 Cur	rent				11.2 New (i	f applicable)	
11.1.1	11.1.2 Supplier	11.1.3	11.1.4	11.1.5	11.1.6	11.2.2	11.2.3	11.2.4	11.2.6
Customer	Part Name	Supplier	Package	Part	Additional	Supplier	Supplier Part	Package	Additional
Part No.		Part No.	Name	Description		Part Name	No.	Name	Part
		(optional)		(optional)	Information		(optional)		Information
	LES 15-NP				(optional)				(optional)
	LES 25-NP			<u> </u>					
	LES 50-NP								
	LES 6-NP LESR 15-NP						1		
	LESR 15-NP/SP1	+	+	+			+		+
	LESR 25-NP								
	LESR 25-NP/SP1								
	LESR 50-NP								

	LESR 6-NP					
	LESR 6-NP/SP1					
	LKSR 15-NP					
	LKSR 25-NP					
	LKSR 50-NP					
	LKSR 6-NP					
	LKSR 6-NP/SP1					
	LKSR 75-NP					
	LPSR 15-NP					
	LPSR 25-NP					
	LPSR 50-NP					
	LPSR 50-NP/SP2					
	LPSR 6-NP					
	LXS 15-NPS					
	LXS 25-NPS					
	LXS 6-NPS					
	LXSR 15-NPS					
	LXSR 25-NPS					
	LXSR 6-NPS					
	LASK U-INFS					
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Custon	ner Feedback/Approval Form						
	Tit	le of PCN:					
	Primary pins+platin	g supplier & pla	ating process				
Custo	Supplier PCN No. PCN-037_2025_0-OMTS2512701						
	check the appropriate box below:						
1. feedl	back to be provided within 3 weeks after		of the PCN.				
Ш	1. Feedback	date:					
	We agree with this proposed change for Approval letter will be sent in written for		sted in chapte	r '11. Affected parts'.			
	We agree with this proposed change sch letter will be sent in written form after ev		I start with the	PCN process. Approval			
	We disapprove because:						
	Remark:						
2. feedl	back to be provided within 6 weeks after	the reception	of the PCN.				
	2. Feedback	date:					
	We acknowledge qualification / validatio	n as assigned	in chapter 8 o	f the PCN.			
	We need more information:						
	We need the following samples:						
	Estimated closing date for PCN:						
	Final Foodback/Approval	date:					
	Final Feedback/Approval	uate:					

	Sender:		
Company:			
Name:			
Address/Location:			
Signature:			
Date:			

	Please return to: [your Sales partner]				
Name:	Magdalena Peycheva - Product Life Cycle Coordinator				
Address/Location:					
Phone:					
Fax:					
Email:	Mpy@lem.com				

In case LEM does not receive any feedback within 6 weeks at the latest after PCN notification, LEM will assume:

- Customer acceptance to the change
- No need for samples
- No additional need

- 1. feedback to be provided within 3 weeks after the reception of the PCN.
- 2. feedback to be provided within 6 weeks after the reception of the PCN.

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- Customer acceptance to the change
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